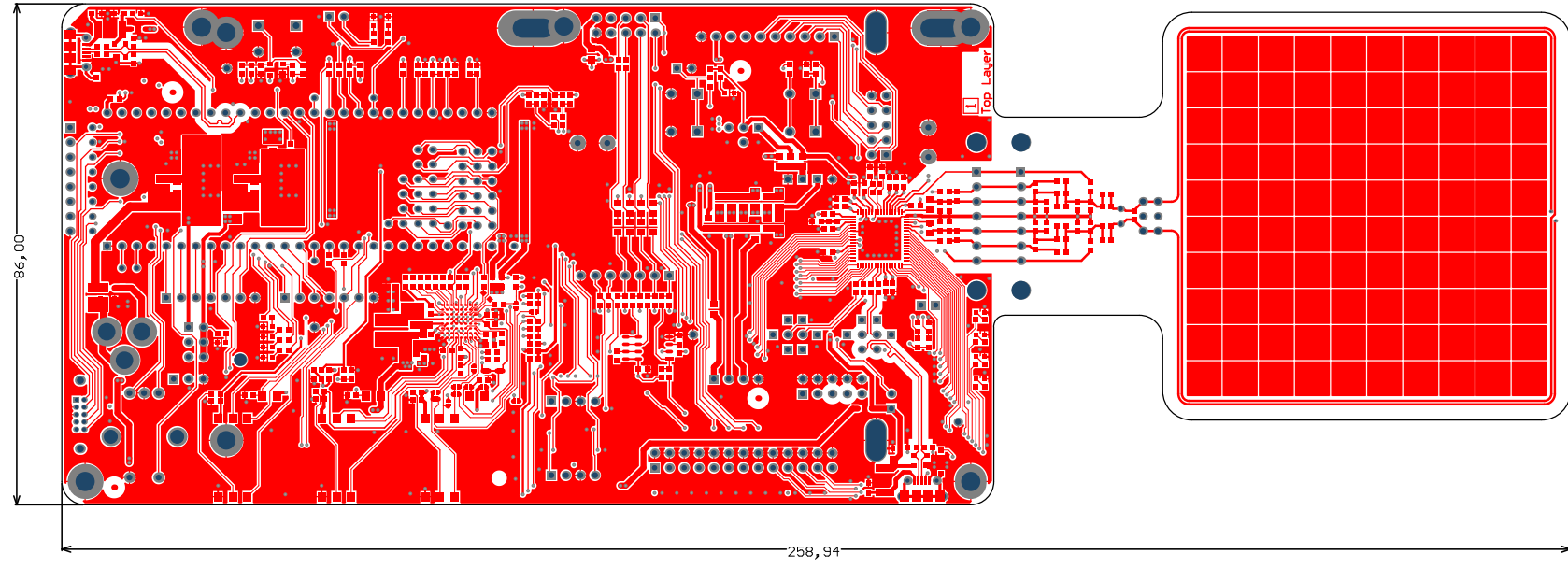
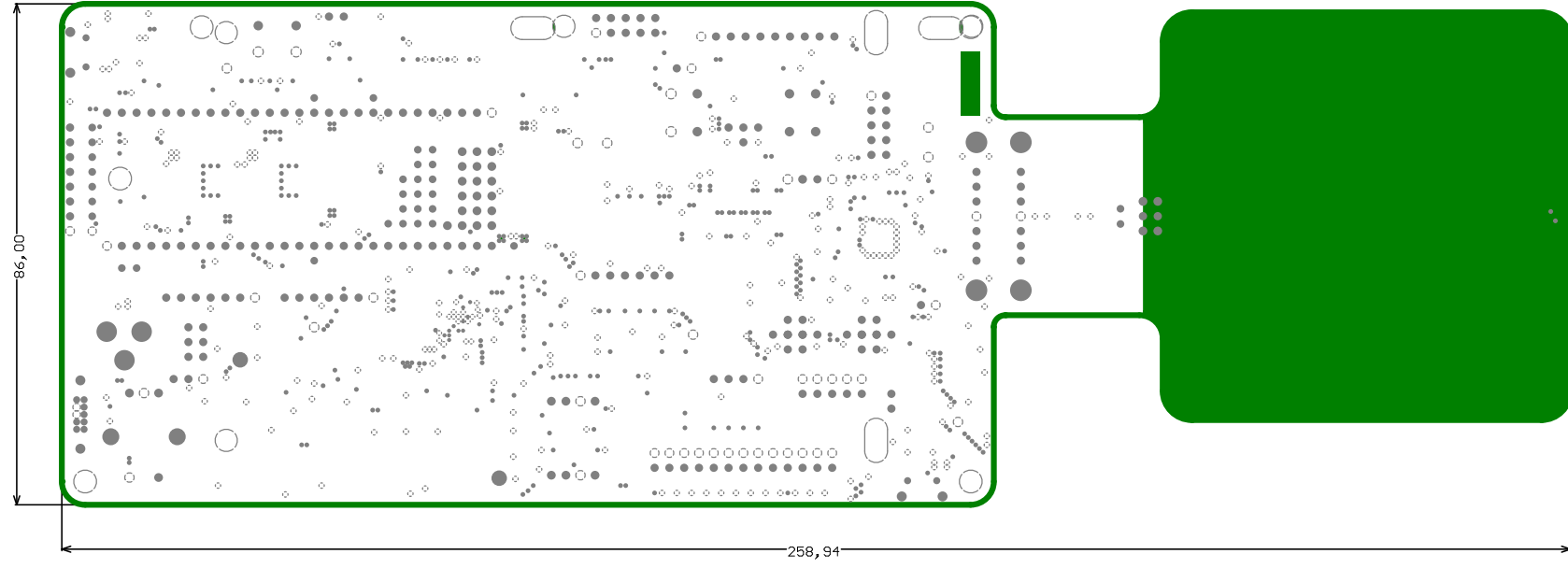
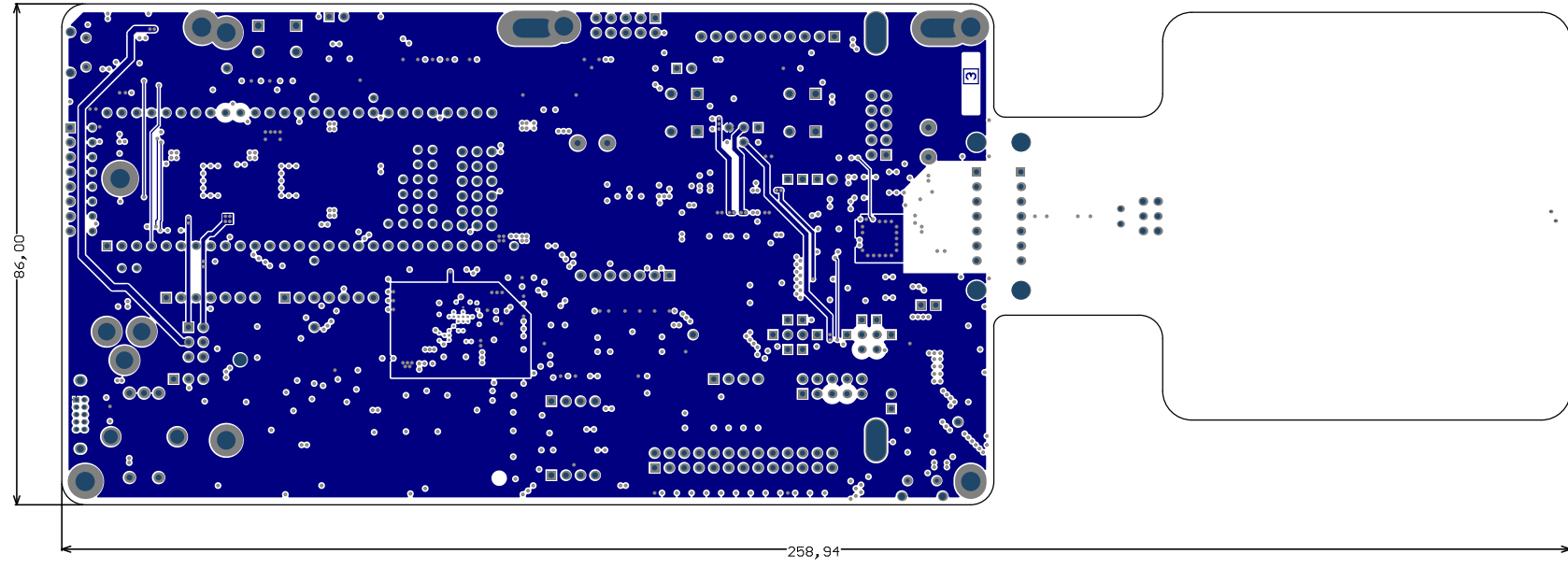
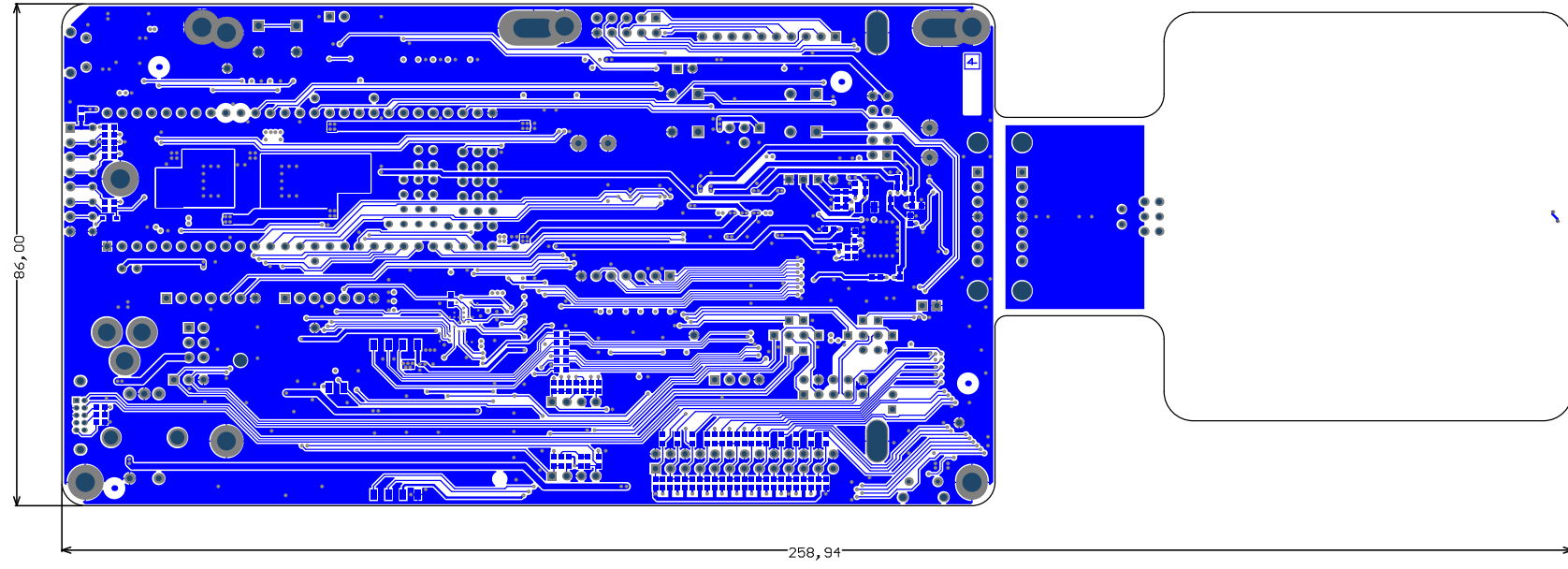
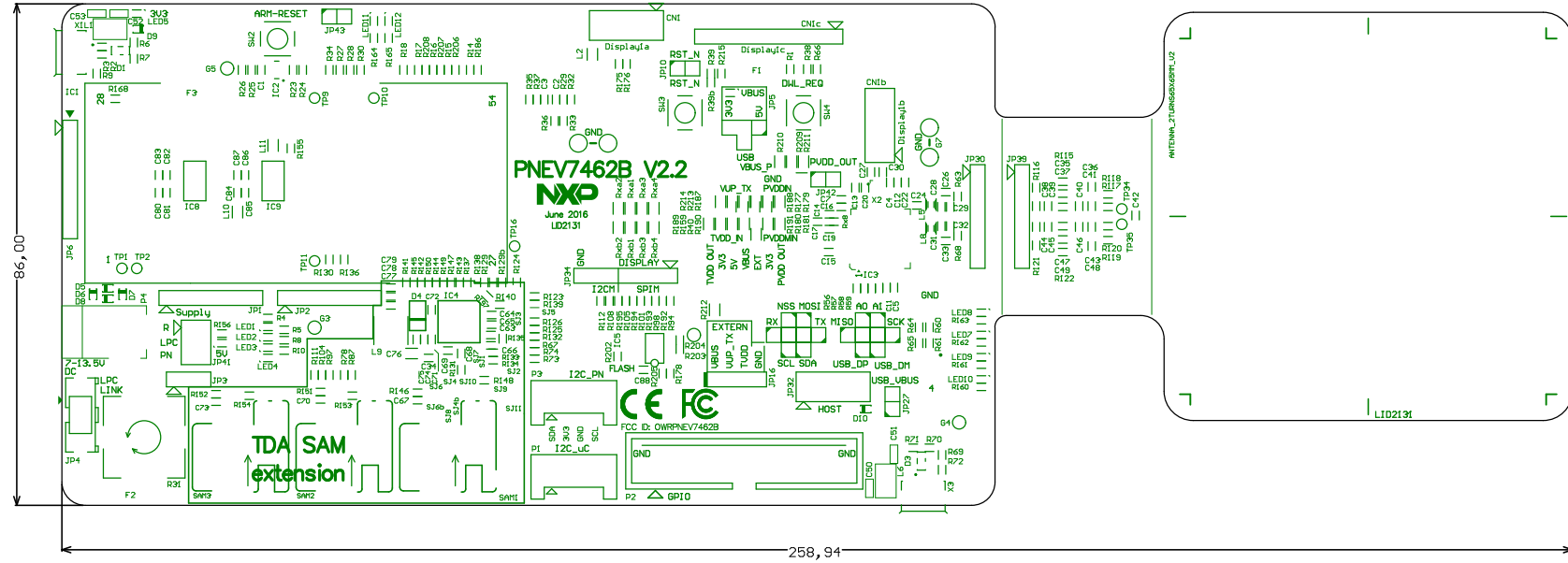


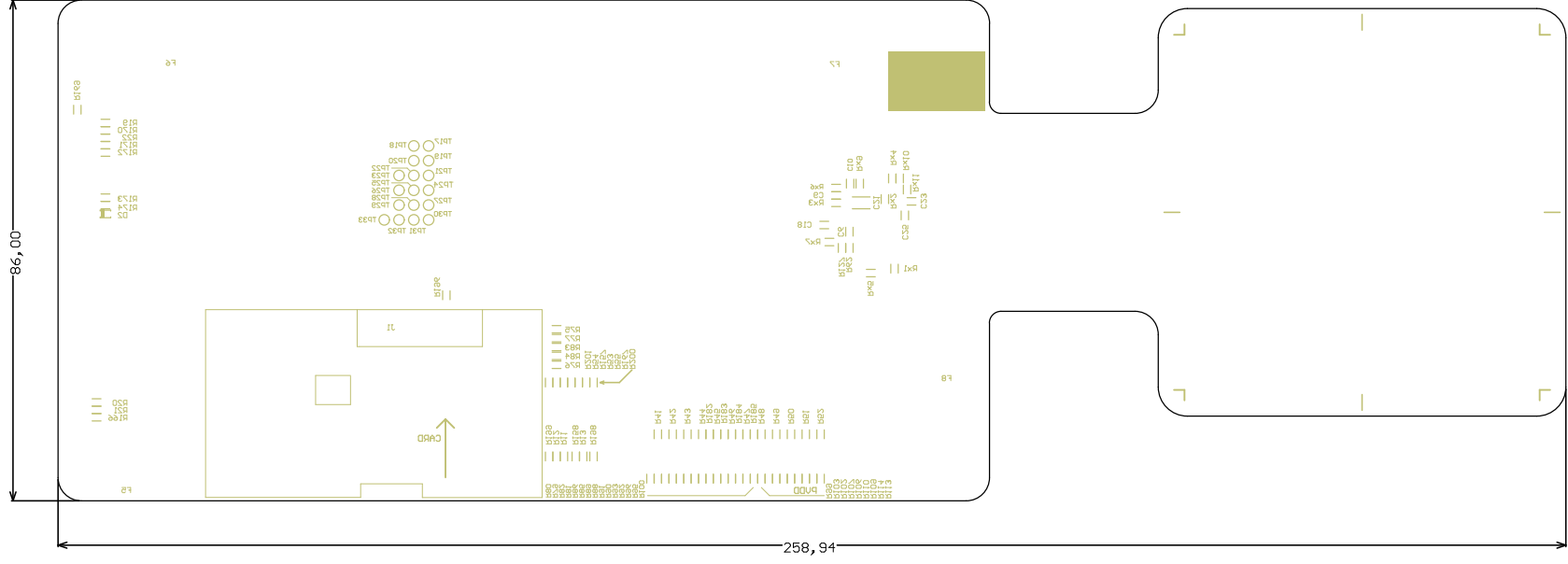


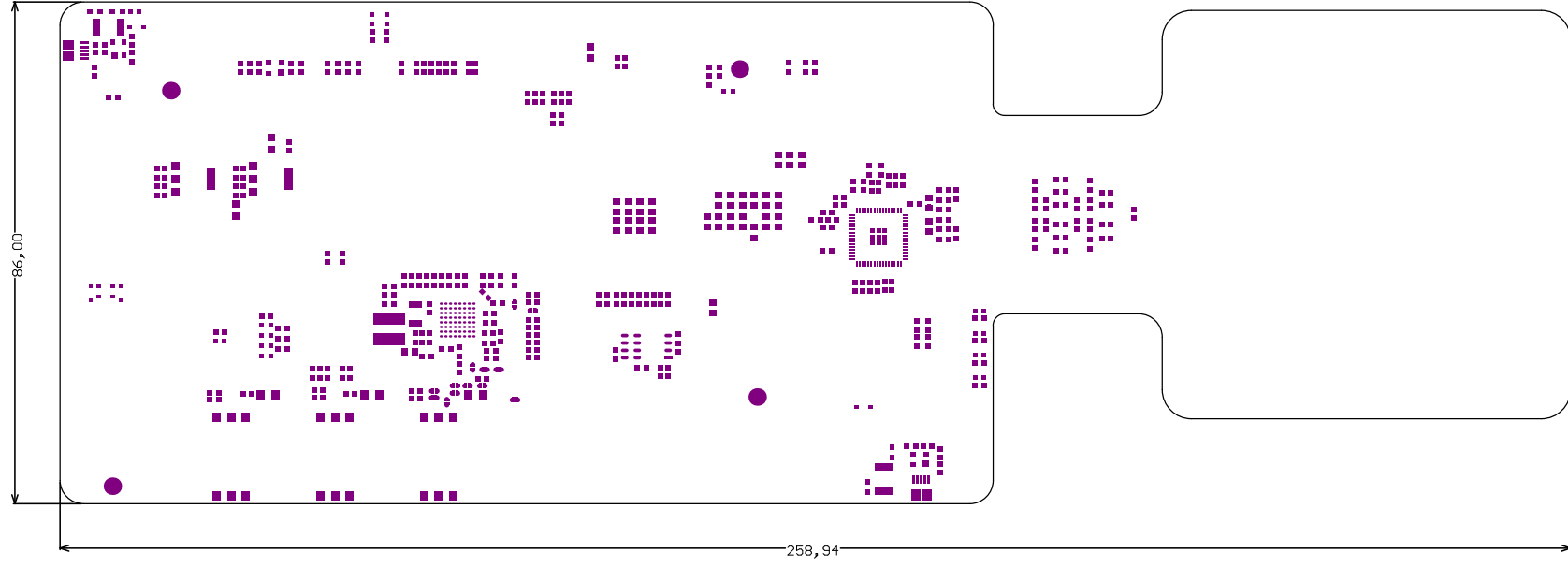


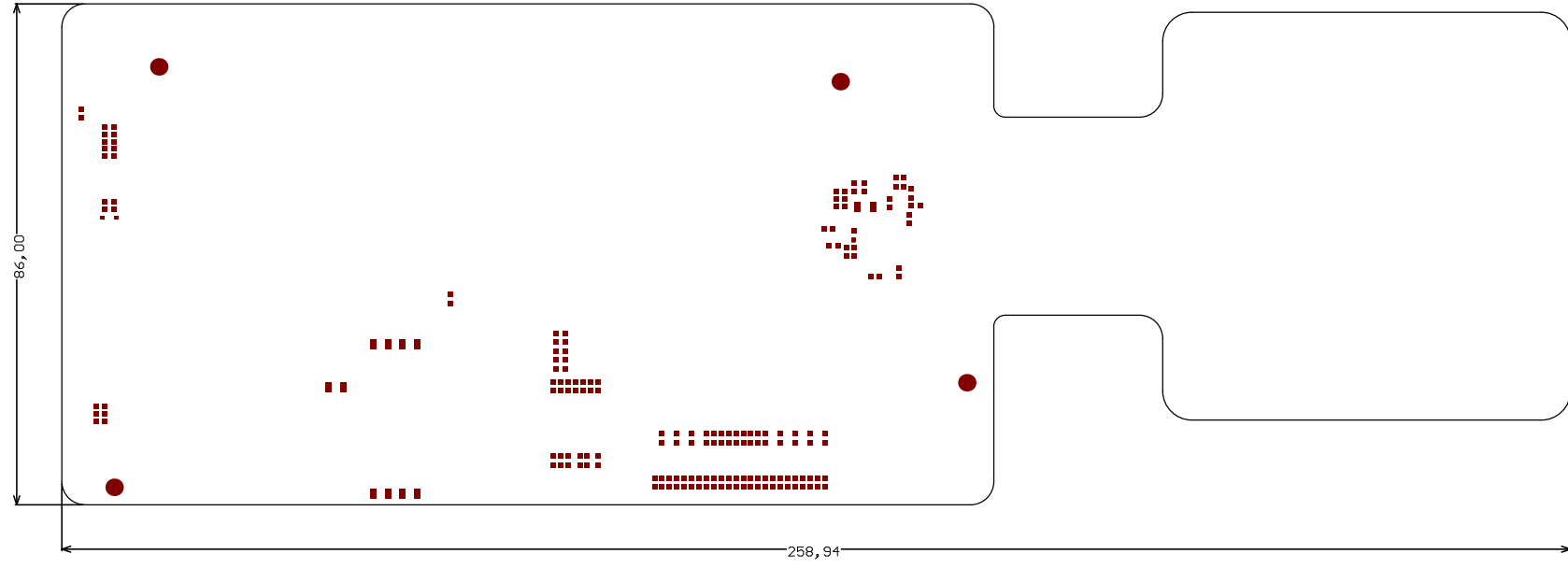


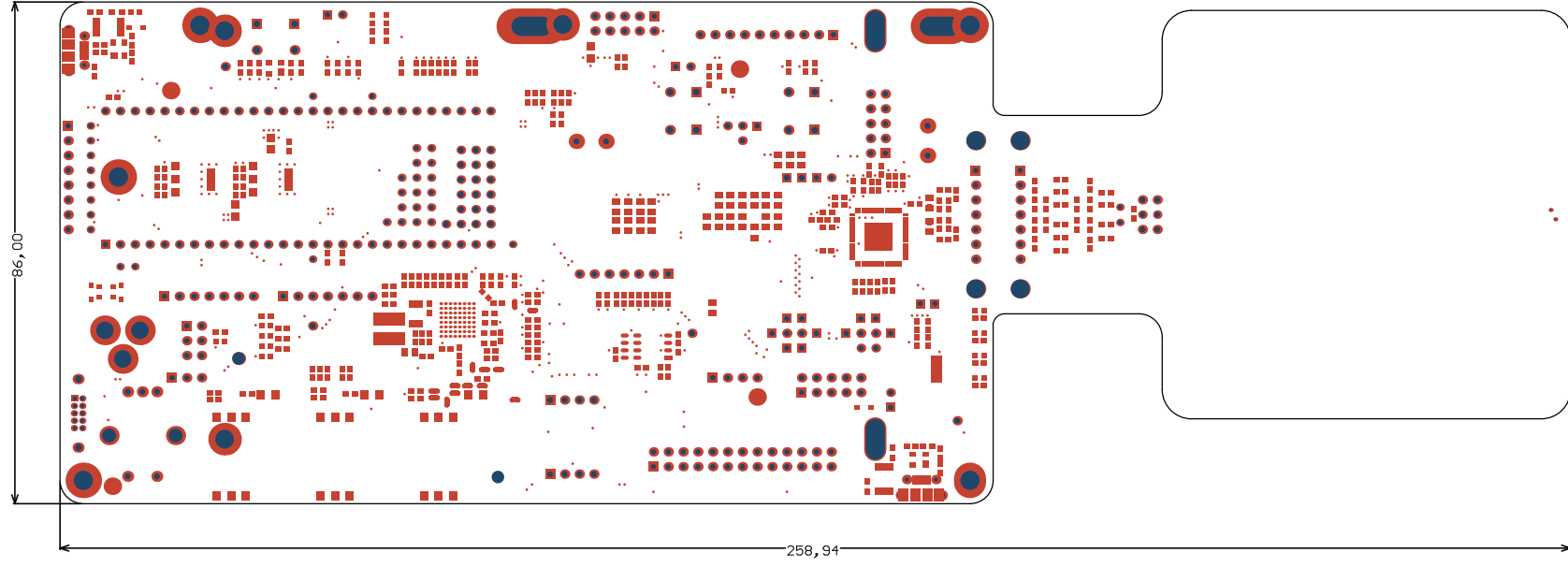


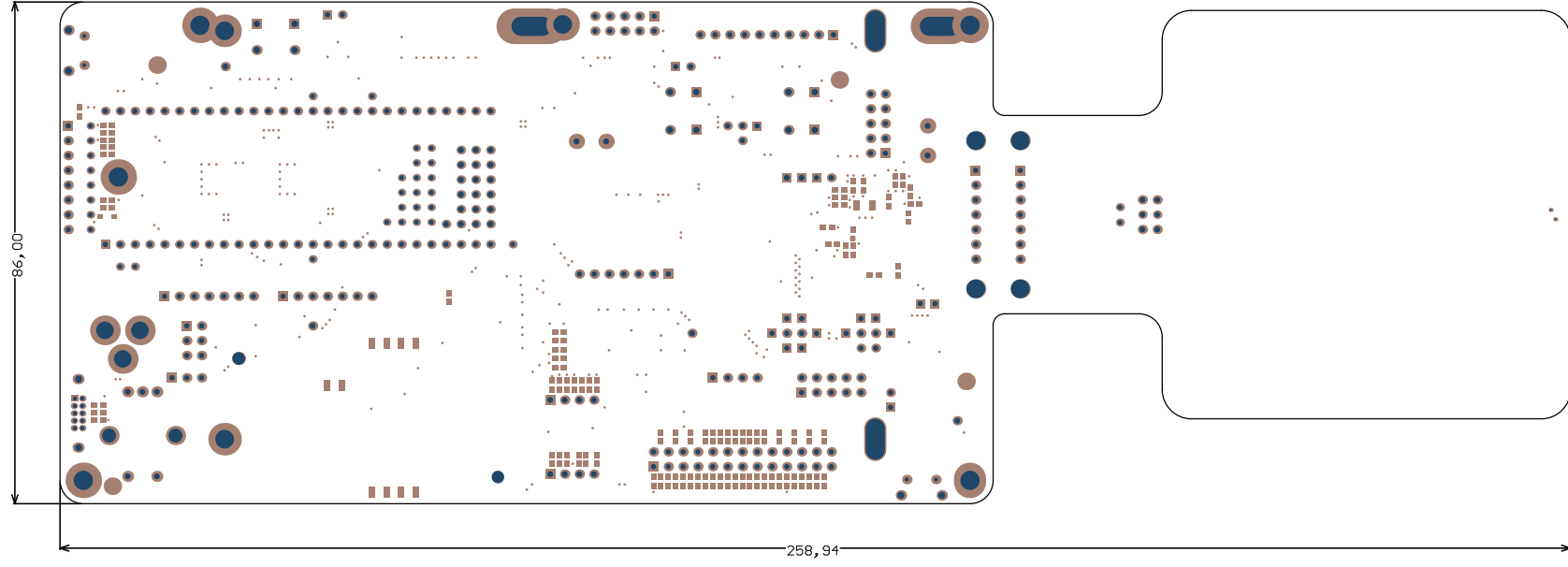


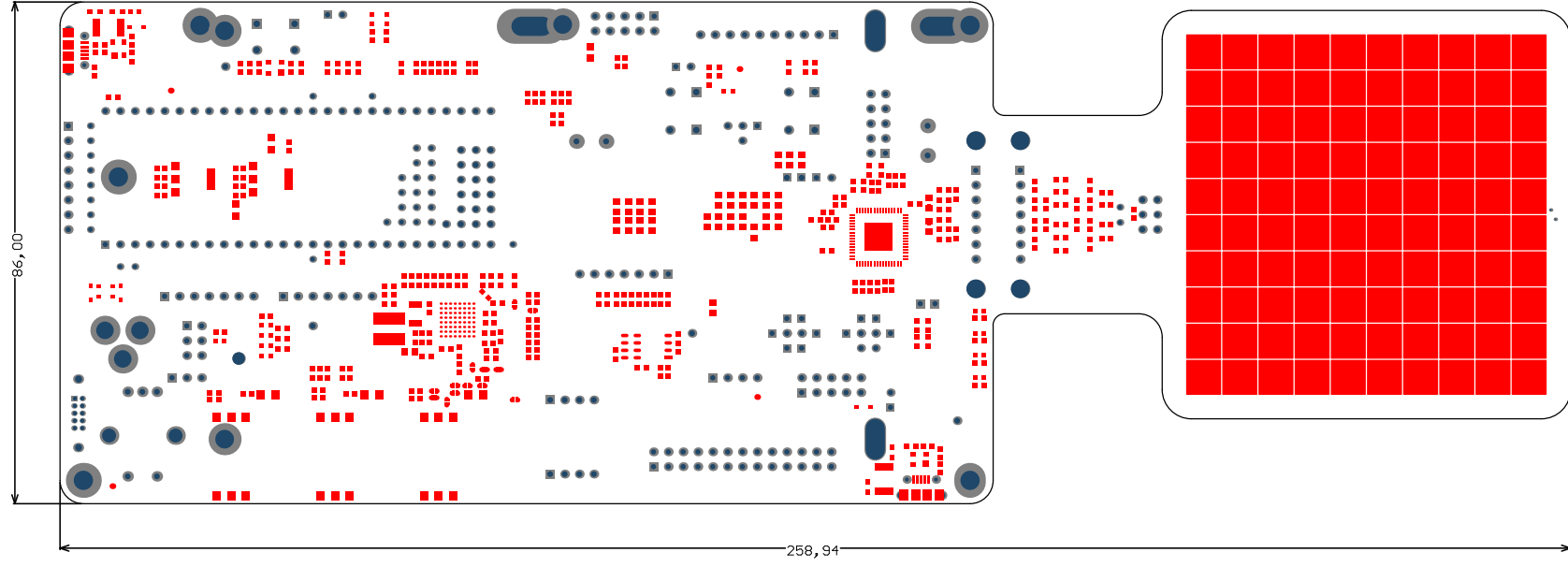


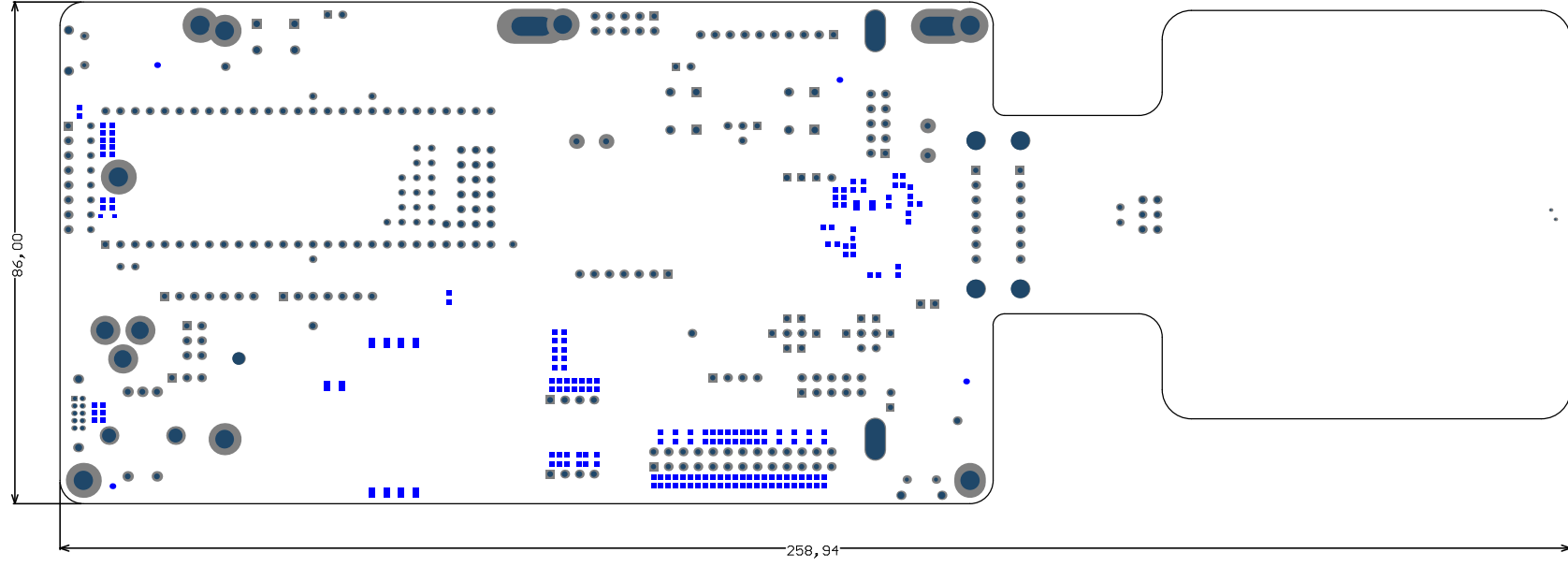












Master Drawings:

- material: FR4, Tg: 150
- thickness: 1,6mm (min 1,44, max 1,7mm)
- layer stackup: - Top Cu: 35um
 - prepreg 0,28mm
 - Internal Plane1 Cu: 35um
 - core 1,0mm
 - MidLayer1 Cu: 35um
 - prepreg 0,28mm
 - Bottom Cu: 35um
- min. hole metalization: 20um
- surface finishing: ENIG
- solder mask: - in accordance with IPC-SM-840
 - Liquid Photo Imageable (LPI)
 - color: GREEN
 - unless otherwise defined (in gerber), solder mask overlap on SMT pads is not allowed
- silk screen: Yes, White
- impedance control: Yes, see table below
- board must meet the acceptable level of IPC-A-600, Class 2, current revision,
- bow and twist: - max, 0,75% SMT boards
- max, 1,5% THT boards
- point of origin (0,0): bottom left corner
- board is designed on 0,050 mm grid
- primary side: Top layer

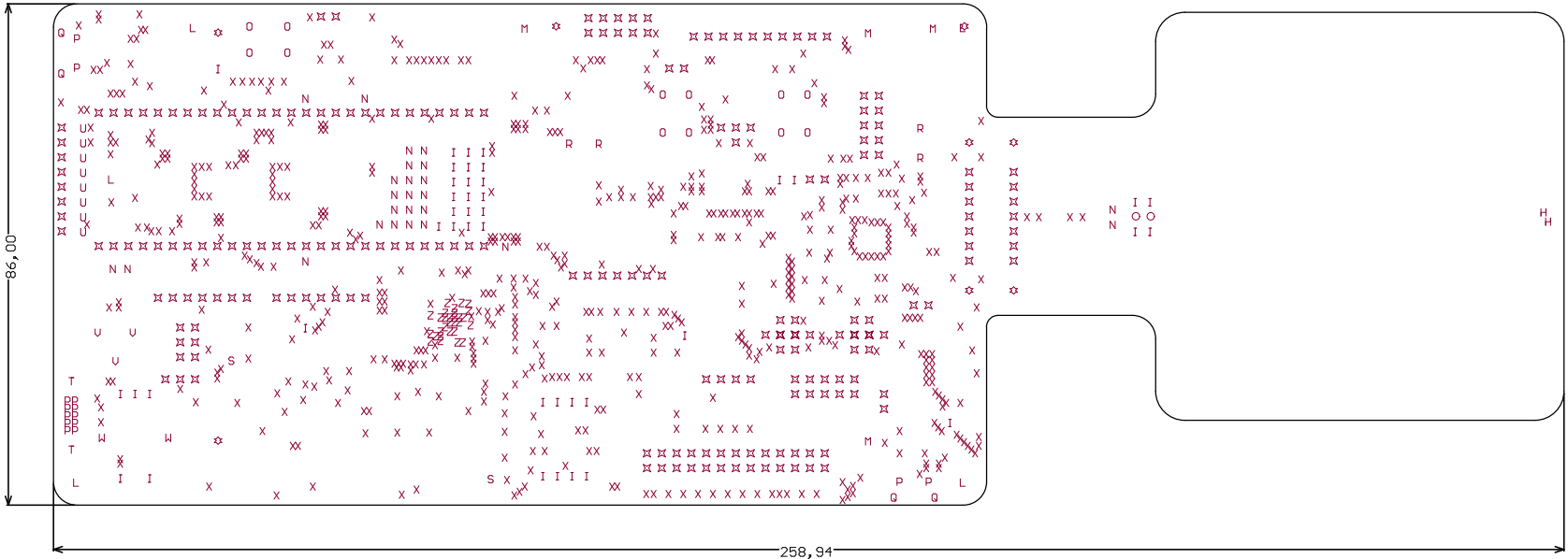
Impedance table:

	Differential pair 90 [ohm] Width / Spacing [mm]
Layer1	0,22 / 0,3
Layer2	
Layer3*	0,18 / 0,40
Layer4	0,22 / 0,3

*- not used

Symbol	Count	Hole Size	Plated	Hole Type	Via/Pad	Hole Length
Z	29	0,200mm	PTH	Round	Via	-
X	618	0,300mm	PTH	Round	Via	-
H	2	0,305mm	PTH	Round	Pad	-
P	14	0,700mm	PTH	Round	Pad	-
N	25	0,800mm	PTH	Round	Pad	-
U	8	0,813mm	PTH	Round	Pad	-
И	214	0,900mm	PTH	Round	Pad	-
O	2	0,914mm	PTH	Round	Pad	-
I	42	1,000mm	PTH	Round	Pad	-
R	4	1,016mm	PTH	Round	Pad	-
O	12	1,118mm	PTH	Round	Pad	-
T	2	1,200mm	NPTH	Round	Pad	-
Q	4	1,200mm	PTH	Round	Pad	-
S	2	2,150mm	PTH	Round	Pad	-
W	2	2,400mm	PTH	Round	Pad	-
U	3	3,000mm	PTH	Round	Pad	-
Ø	8	3,200mm	PTH	Round	Pad	-
L	5	3,300mm	PTH	Round	Pad	-
	4	3,300mm	PTH	Slot	Pad	7,000mm
	1000	Total				

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer (*,GTL)	Copper	0,035mm		
4	Dielectric1	IS400/TG150	0,280mm	4,2	
5	Internal Plane 1 (*,GPI)	Copper	0,035mm		
6	Dielectric2	IS400/TG150	1,000mm	4,2	
7	Mid-Layer 1 (*,GI)	Copper	0,035mm		
8	Dielectric3	IS400/TG150	0,280mm	4,2	
9	Bottom Layer (*,GBL)	Copper	0,035mm		
10	Bottom Solder	Solder Resist	0,010mm	3,5	
11	Bottom Overlay				